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500.40269X00
Expedited Procedure
Group No. 1753

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: HABA et al.
Application No.: 09/888,642
Filed: June 26, 2001
For: ELECTRIC COPPER PLATING LIQUID AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR INTEGRATED
CIRCUIT DEVICE USING SAME
Art Unit: 1753
Examiner: E. Wong

AMENDMENT AFTER FINAL REJECTION

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 25, 2004

Sir:

In response to the Office Action mailed March 25, 2004, please amend the
above-identified application as listed in the following, and as set forth on the
following pages:

Amendments to the Claims; and

Remarks are included following the amendments.